



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Biswajit Sur et al.

Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL INTERFACE AND  
METHODS OF MANUFACTURE

Docket No.: 884.319US2

Filed: February 9, 2004

Examiner: Andy Huynh

Customer No.: 21186

Serial No.: 10/775,890

Due Date: April 17, 2006

Group Art Unit: 2818

Confirmation No.: 1421

Commissioner for Patents

Attn: MAIL STOP ISSUE FEE

P.O. Box 1450

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**Notice of Allowance Date:**

January 17, 2006

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☒ Communication Concerning Related Application(s) (1 pg.)

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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number: 21186

By Ann M. McCrackin

Ann M. McCrackin

Reg. No. 42,858

AMM1:CMG:clh

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Attn – MAIL STOP ISSUE FEE, P.O. Box 1450, Alexandria, VA 22313-1450, on this 17 day of April, 2006.

Chris Hammond  
Name

Chris Hammond  
Signature

S/N 10/775,890

APR 20 2006

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Biswajit Sur et al. Examiner: Andy Huynh  
Serial No.: 10/775,890 Group Art Unit: 2818  
Filed: February 9, 2004 Docket: 884.319US2  
Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE  
THERMAL INTERFACE AND METHODS OF MANUFACTURE  
Assignee: Intel Corporation Customer No. 21186

**COMMUNICATION CONCERNING RELATED APPLICATION(S)**

MS Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/652430	August 31, 2000	884.319US1	ELECTRONIC ASSEMBLY
6724078	April 20, 2004		COMPRISING SOLDERABLE THERMAL INTERFACE (As Amended)

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,  
BISWAJIT SUR ET AL.  
By their Representatives,  
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
Attorneys for Intel Corporation  
P.O. Box 2938  
Minneapolis, MN 55402  
(612) 349-9592

Date April 17, 2006 By Ann M. McCrackin  
Ann M. McCrackin  
Reg. No. 42,858

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Chris Hammond  
Name

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